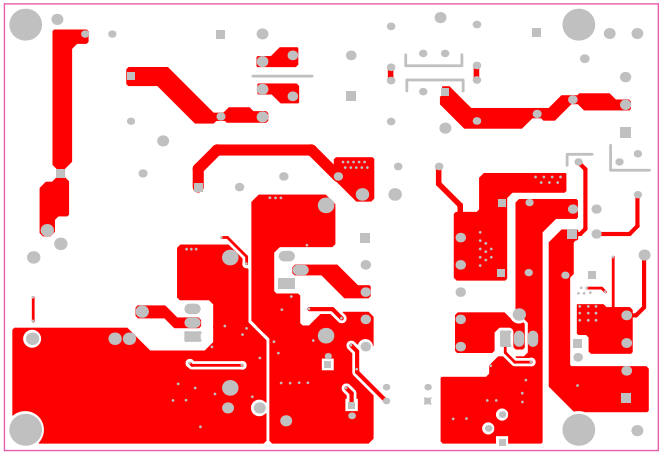
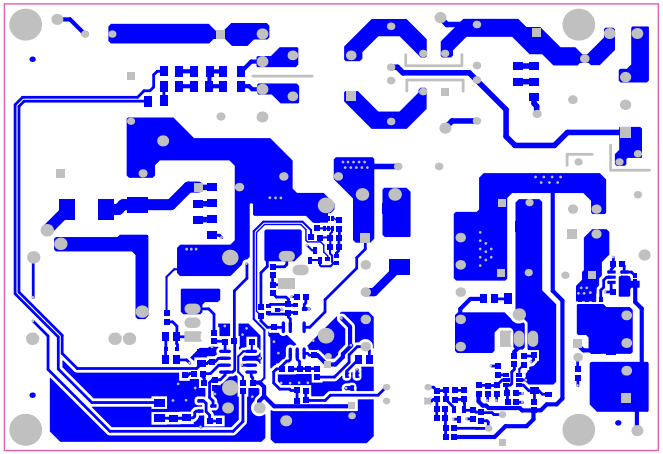
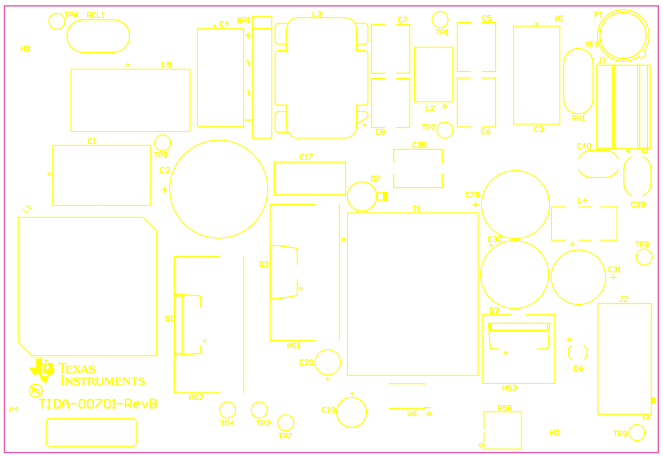


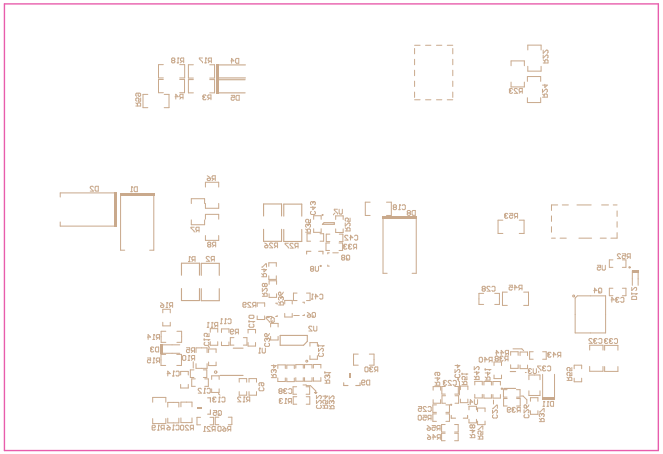
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/24/2015 3:14:29 PM		TEXAS INSTRUMENTS



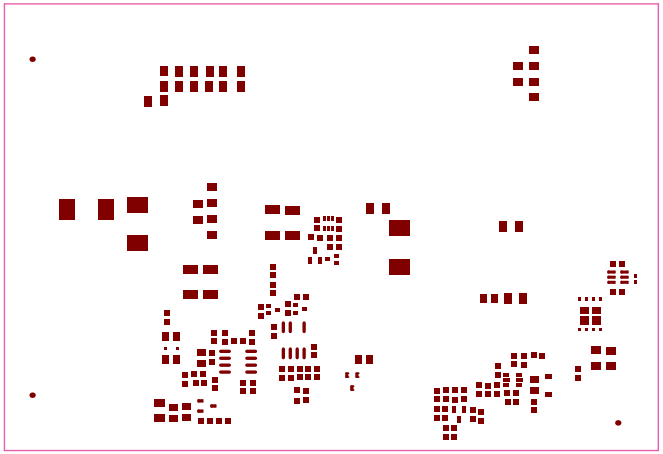
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/24/2015 3:14:30 PM		TEXAS INSTRUMENTS



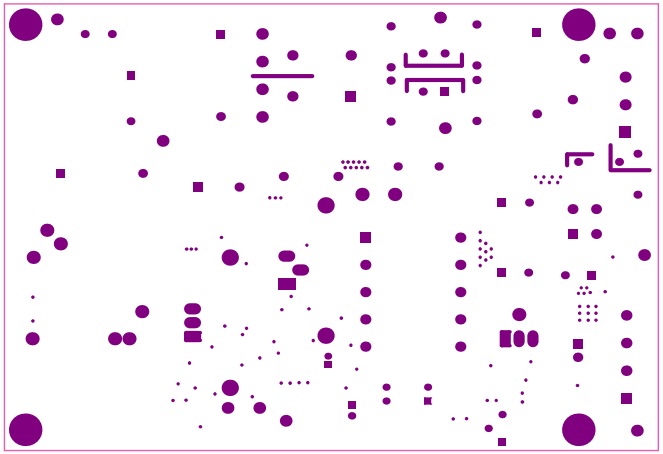
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl	
LAYER NAME = Top Overlay				
PLOT NAME = Top Silkscreen Overlay	GENERATED : 11/24/2015 3:14:30 PM			TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 11/24/2015 3:14:31 PM		TEXAS INSTRUMENTS



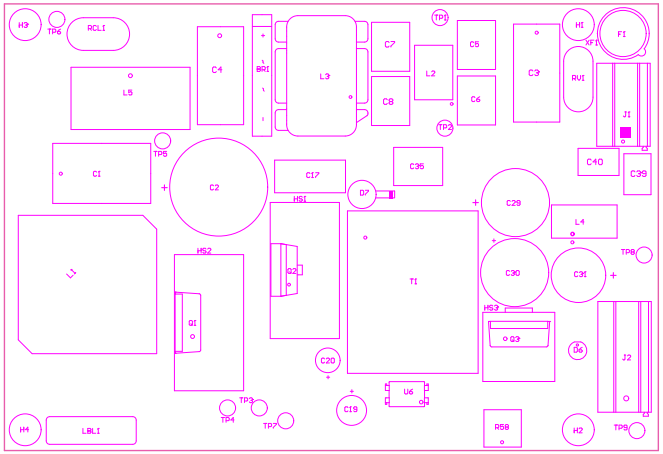
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom Paste Mask Print	GENERATED : 11/24/2015 3:14:31 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask Print	GENERATED : 11/24/2015 3:14:32 PM		TEXAS INSTRUMENTS

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl	
LAYER NAME = Bottom Solder				
PLOT NAME = Bottom Solder Mask Print	GENERATED : 11/24/2015 3:14:32 PM			TEXAS INSTRUMENTS

ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
IGNORE -> M5 Assembly Top			
PLOT NAME = M5 Assembly Top	GENERATED : 11/24/2015 3:14:33 PM		TEXAS INSTRUMENTS

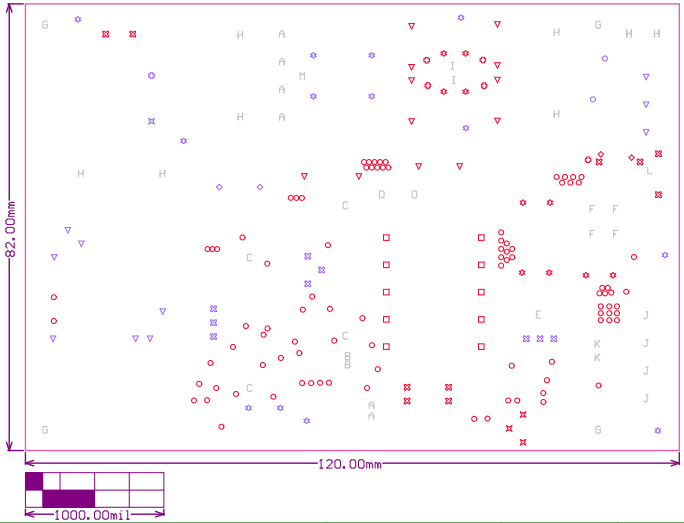
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
	IGNORE -> M6 Assembly Bottom		
PLOT NAME = M6 Assembly Bottom	GENERATED : 11/24/2015 3:14:33 PM		TEXAS INSTRUMENTS

Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
○	92	12mil (0.305mm)			PTH	Round
B	2	27.559mil (0.7mm)			PTH	Round
⌑	3	28.11mil (0.714mm)			PTH	Round
A	2	29.528mil (0.75mm)			PTH	Round
○	1	32mil (0.813mm)			PTH	Round
⌑	1	32.008mil (0.813mm)			PTH	Round
⊠	10	33.465mil (0.85mm)			PTH	Round
✡	10	33.622mil (0.854mm)			PTH	Round
▽	12	35.433mil (0.9mm)			PTH	Round
K	2	35.984mil (0.914mm)			PTH	Round
H	10	39.37mil (1mm)			PTH	Round
✡	13	40mil (1.016mm)			PTH	Round
◇	2	41.496mil (1.054mm)			PTH	Round
○	2	43.307mil (1.1mm)			PTH	Round
F	4	47.244mil (1.2mm)			PTH	Round
□	10	49.213mil (1.25mm)			PTH	Round
⊠	9	50mil (1.27mm)			PTH	Round
J	4	51.181mil (1.3mm)			PTH	Round
▽	10	52mil (1.321mm)			PTH	Round
A	4	59.055mil (1.5mm)			PTH	Round
D	2	61.024mil (1.55mm)			PTH	Round
E	1	70.094mil (1.78mm)			PTH	Round
C	4	92.913mil (2.36mm)			PTH	Round
G	4	125mil (3.175mm)			PTH	Round
✡	5	20mil (0.508mm)	100mil (2.54mm)	80mil (2.032mm)	NPTH	Slot
◇	2	20mil (0.508mm)	200mil (5.08mm)	180mil (4.572mm)	NPTH	Slot
L	1	20mil (0.508mm)	300mil (7.62mm)	280mil (7.112mm)	NPTH	Slot
I	2	20mil (0.508mm)	425mil (10.795mm)	405mil (10.287mm)	NPTH	Slot
M	1	20mil (0.508mm)	450mil (11.43mm)	430mil (10.922mm)	NPTH	Slot
	225 Total					

Slot definitions : **Rout Path Length** = Calculated from tool start centre position to tool end centre position.
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL



Layer Stack Up Detail for: TIDA-00701-RevB.PcbDoc

Layer Name	Barber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
			59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
120 MM X 82 MM

Number of Layers : 2
MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA DRILL SIZE: 12 MIL
MINIMUM ANNULAR RING 0.111mm (4.39 MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [ ] NO [X]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: 100W NEC Class-2,DIN Rail Industrial Power Supply
DESIGNED FOR: Public Release
FILE NAME: TIDA-00701_RevB.PcbDoc

ENGINEER: Latif Ameer	LAYOUT BY: Manjunatha T N
SCALE: 0.72	ALTIUM DESIGNER VERSION: 14.3.14.34663

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00701	REV: RevB	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing For (Bottom Layer)	GENERATED: 11/24/2015 3:14:34 PM		TEXAS INSTRUMENTS

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